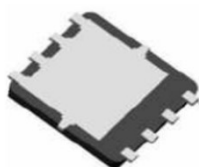
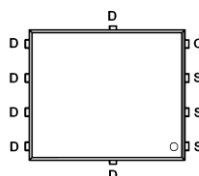


**Main Product Characteristics:**

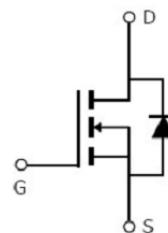
$V_{DSS}$	100V
$R_{DS(on)}$	4.2m $\Omega$ (typ.)
$I_D$	140A



PDFN5x6-8L



Pin Assignments



Schematic Diagram

**Features and Benefits:**

- Advanced MOSFET process technology
- Special designed for PWM, load switching and general purpose applications
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- 150°C operating temperature


**Description:**

It utilizes the latest processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in power switching application and a wide variety of other applications.

**Absolute Max Rating:**

Symbol	Parameter	Max.	Units
$I_D @ T_c = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ ①	140	A
$I_D @ T_c = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ ①	85	
$I_{DM}$	Pulsed Drain Current ②	417	
$P_D @ T_c = 25^\circ\text{C}$	Power Dissipation ③	266	W
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy @ $L=0.5\text{mH}$	380	mJ
$I_{AS}$	Avalanche Current	39	A
$T_J \quad T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

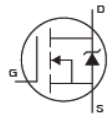
## Thermal Resistance

Symbol	Characterizes	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-case ③	—	0.47	°C/W

## Electrical Characterizes @ $T_A=25^\circ\text{C}$ unless otherwise specified

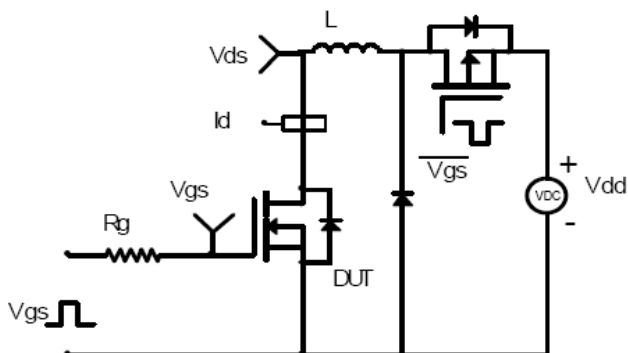
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source breakdown voltage	100	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$R_{DS(on)}$	Static Drain-to-Source on-resistance	—	4.2	6	m $\Omega$	$V_{GS}=10V, I_D = 20A$
$V_{GS(th)}$	Gate threshold voltage	2	—	4	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
$I_{DSS}$	Drain-to-Source leakage current	—	—	1	$\mu A$	$V_{DS} = 100V, V_{GS} = 0V$
$I_{GSS}$	Gate-to-Source forward leakage	—	—	100	nA	$V_{GS} = 20V$
		—	—	-100		$V_{GS} = -20V$
$C_{iss}$	Input capacitance	—	3820	—	pF	$V_{GS} = 0V$
$C_{oss}$	Output capacitance	—	589	—		$V_{DS} = 50V$
$C_{rss}$	Reverse transfer capacitance	—	18	—		$f = 100kHz$
$Q_g$	Total gate charge	—	42	—	nC	$I_D = 20A,$
$Q_{gs}$	Gate-to-Source charge	—	12	—		$V_{DS}=50V,$
$Q_{gd}$	Gate-to-Drain("Miller") charge	—	10	—		$V_{GS} = 10V$
$t_{d(on)}$	Turn-on delay time	—	29.4	—	ns	$V_{GS}=10V, V_{DS} = 50V,$ $R_{GEN}=3.6\Omega, R_L=2.2\Omega$
$t_r$	Rise time	—	44	—		
$t_{d(off)}$	Turn-Off delay time	—	47	—		
$t_f$	Fall time	—	12	—		

## Source-Drain Ratings and Characteristics

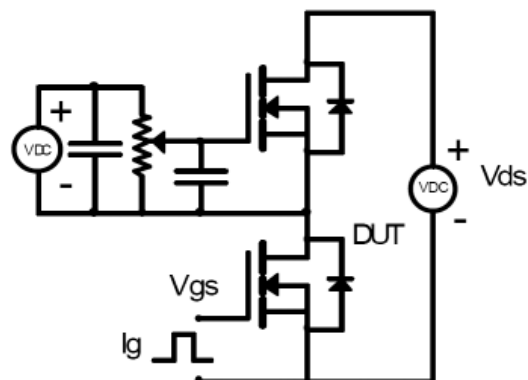
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	167	A	MOSFET symbol showing the integral reverse p-n junction diode. 
$I_{SM}$	Pulsed Source Current (Body Diode)	—	—	417	A	
$V_{SD}$	Diode Forward Voltage	—	—	1.2	V	$I_S=20A, V_{GS}=0V$
$t_{rr}$	Reverse Recovery Time	—	61	—	ns	$T_J = 25^\circ\text{C}, I_F = 20A, di/dt =$
$Q_{rr}$	Reverse Recovery Charge	—	62	—	nC	100A/ $\mu s$

## Test Circuits and Waveforms

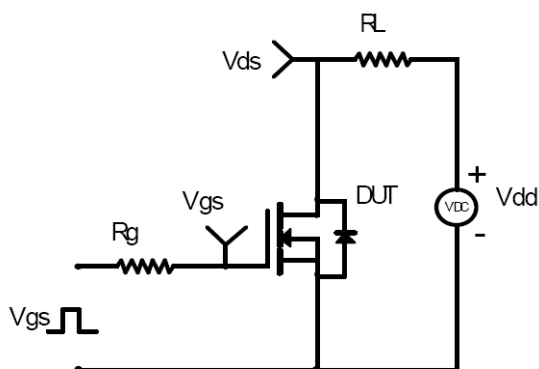
EAS Test Circuit:



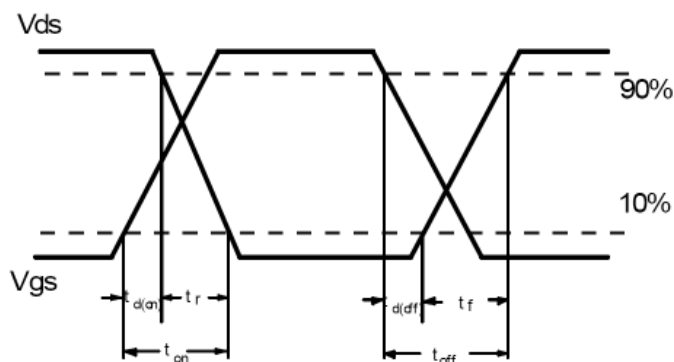
Gate Charge Test Circuit:



Switching Time Test Circuit:



Switching Waveforms:



### Notes:

- ① Calculated continuous current based on maximum allowable junction temperature.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ The power dissipation  $P_D$  is based on max. junction temperature, using junction-to-case thermal resistance.

Typical Electrical and Thermal Characteristics

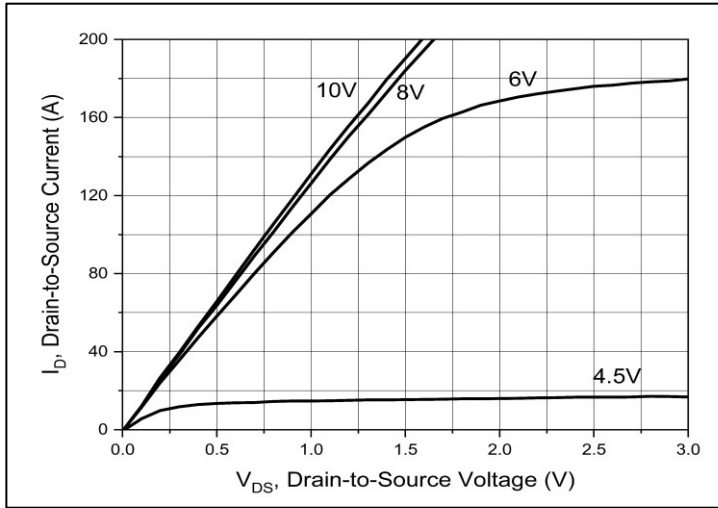


Figure1. Typical Output Characteristics

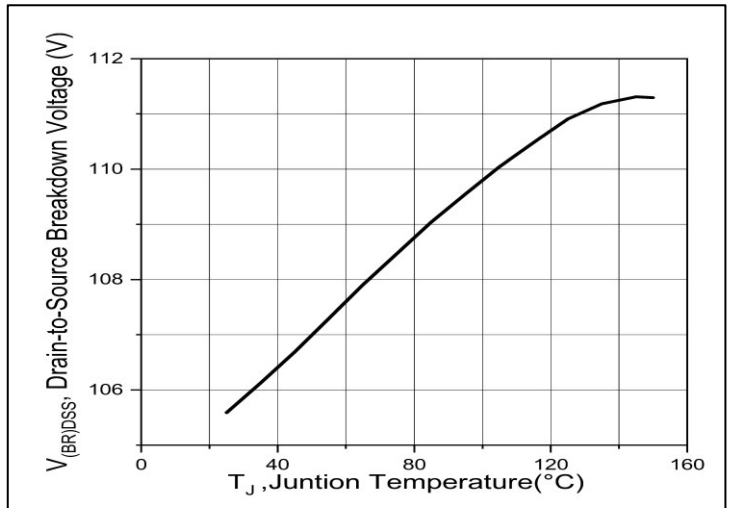


Figure2. Drain-to-Source Breakdown Voltage vs. Junction Temperature

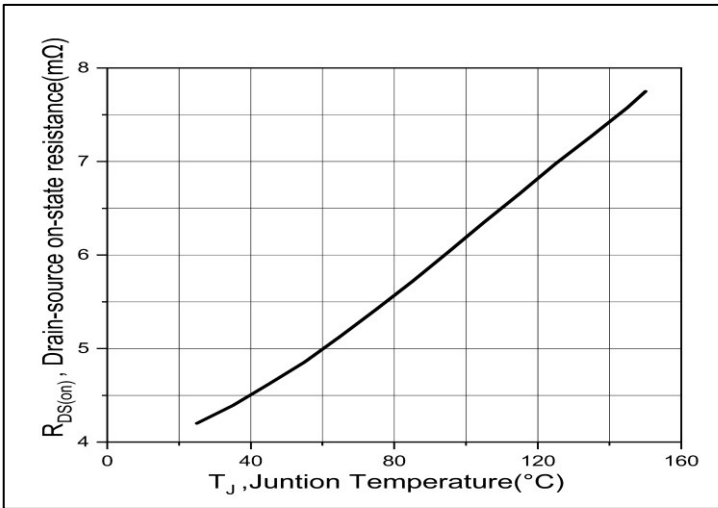


Figure3. R\_DS(on) vs. Junction Temperature

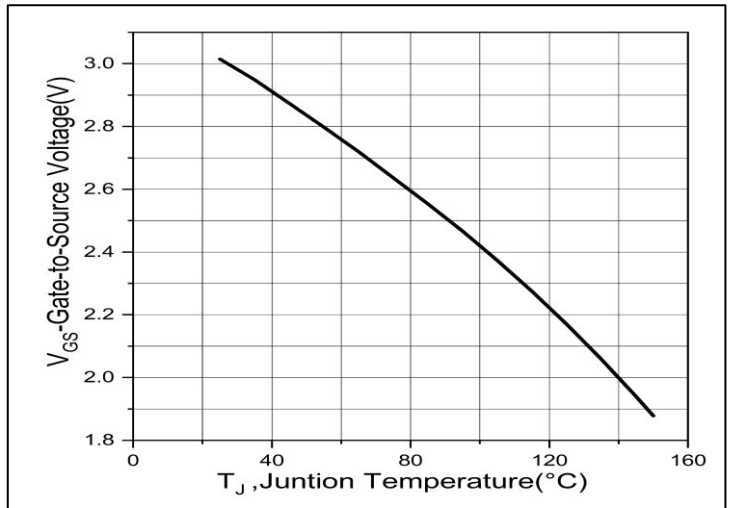


Figure4. V\_{th} vs. Junction Temperature

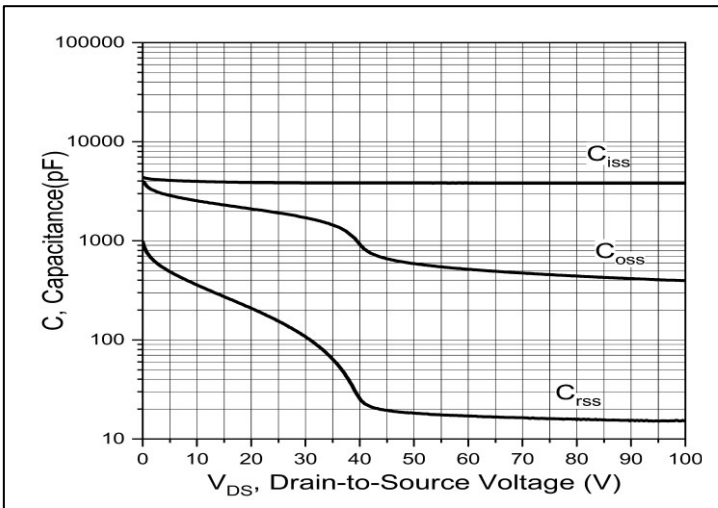


Figure5. Capacitance

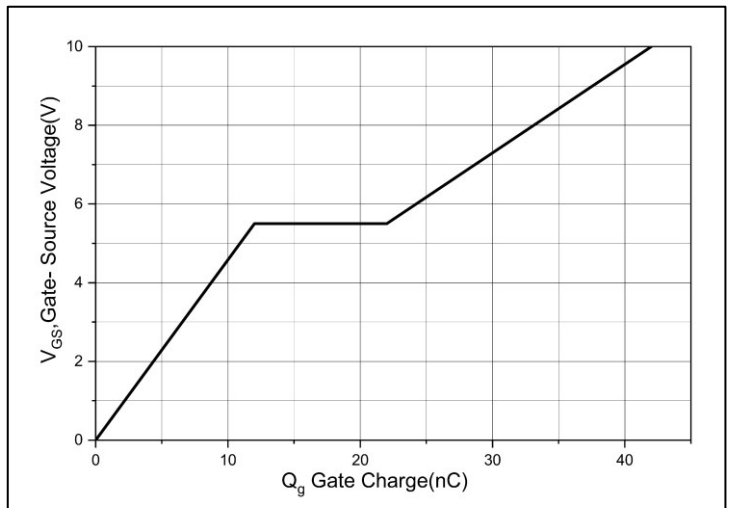


Figure6. Gate Charge

### Typical Electrical and Thermal Characteristics

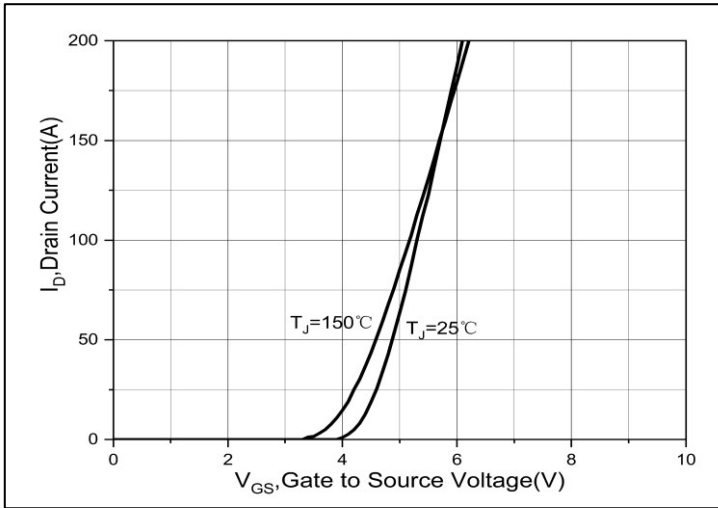


Figure7. Transfer Characteristics

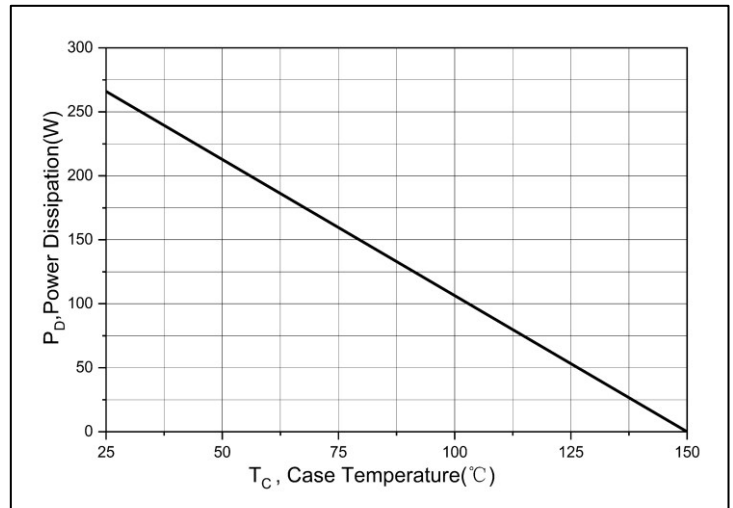
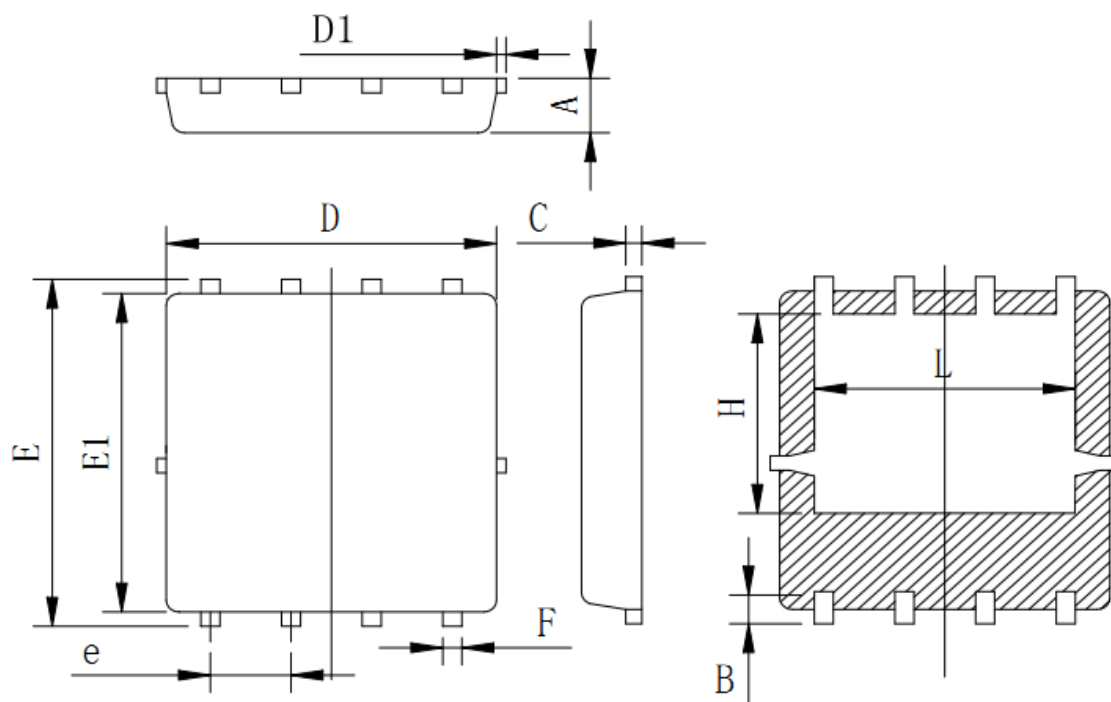


Figure8. Power Dissipation

**Mechanical Data:**


Symbol	Min	Typ	Max
A	0.90	0.95	1.00
B	0.48	0.58	0.68
C	0.20	0.254	0.30
D	5.00	5.20	5.40
D1			0.15
E	5.90	6.05	6.20
E1	5.40	5.55	5.70
e	1.22	1.27	1.32
F	0.25	0.30	0.35
H	3.27	3.47	3.67
L	3.80	4.00	4.20

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